IPC  ASSOCIATION CONN ELECTRONICS INDU	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This do level pa	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfc Information				
upplier Inf	ormation					,			,					
Company name*			Company unique ID			Unique ID Au	Unique ID Authority				Response Date*			
nsemi											2025-06-06			
Contact Name			Title - Contact			Phone - Conta	Phone - Contact*				Email - Contact*			
Product-Env-S	Stewards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com			
uthorized Rep	presentative*		Title - Representative			Phone - Repr	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com			
Req	uester Item Number			Mfr Item Name		Effective Dat	e Versio	on Manufacturing Site		Weight*	UOM	Unit Type		
				Dual 60V 1A Low\	Oual 60V 1A LowVCEsat NPN WDFN6		2025-06-06 MY1		MY1	9.62	mg	Each		
	ing Proccess Informa		erminal Base A	Alloy	STD-020 MSL Rating	Dook Dro	cass Rody	Tamparati	ure Max Time at Peak	Tamparatura N	umber of Reflow Cy	volas		
		CU Alloy 1		31D-020 WISE Rating		Peak Process Body Temperat		30	seconds 3	uniber of Kerlow Cy	cies			
omments	ic in (511) - anneaicu		O Alloy	1		200		10	150	seconds 3				
	um time at peak temperati	uro durina sol	doring is 10-3	A seconds										
	mation regarding material													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.58	mg	Supplier	Silicon (Si)	7440-21-3		0.58	mg
Die Attach	0.17		Supplier	Silver (Ag)	7440-22-4		0.1445	mg
			Supplier	Acrylic resins	Proprietary Data		0.0255	mg
Lead Frame	2.65		Supplier	Tin (Sn)	7440-31-5		0.0066	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0066	mg
			Supplier	Copper (Cu)	7440-50-8		2.6309	mg
Lead Frame plating	0.05	mg	Supplier	Silver (Ag)	7440-22-4		0.05	mg
Mold Compound-Black	5.47			Epoxy resin	proprietary data		0.2571	mg
			Supplier	Phenol Resin	Proprietary Data		0.2571	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0055	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.9503	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg